# Abstracts

## Packaging and Metallisation Effects of Valley Microstrip Line with Slit for Use in Very Small Multilayer MMICs

*A.S. Rong and Z.L. Sun. "Packaging and Metallisation Effects of Valley Microstrip Line with Slit for Use in Very Small Multilayer MMICs." 1994 MTT-S International Microwave Symposium Digest 94.3 (1994 Vol. III [MWSYM]): 1723-1726.*

A comprehensive characterisation of the valley microstrip lines with or without slits is proposed. When applied to very small multilayer MMICs, such new lines exhibit the appreciable packaging and metallisation effects. Moreover, its characteristic parameters can be adjusted by changing the oblique angle and the slit width, which leads to the flexible circuit design.

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